

Number of Components:	Two	Minimum Bond Line Cure Schedule*:	
Mix Ratio By Weight:	1:1	175°C	45 Seconds
Specific Gravity:		150°C	5 Minutes
Part A	2.03	120°C	15 Minutes
Part B	3.07	80°C	3 Hours
Pot Life:	2.5 Days		
Shelf Life:	One year at room temperature		

Note: Container(s) should be kept closed when not in use. For filled systems, mix contents of each container (A & B) thoroughly before mixing the two together. *Please see Applications Note available on our website.

Product Description:

EPO-TEK[®] H20E is a two component, 100% solids silver-filled epoxy system designed specifically for chip bonding in microelectronic and optoelectronic applications. It is also used extensively for thermal management applications due to its high thermal conductivity. It has proven itself to be extremely reliable over many years of service and is still the conductive adhesive of choice for new applications.

EPO-TEK[®] H20E Advantages & Application Notes:

- Especially recommended for use in high speed epoxy chip bonding systems where very fast cures are desired.
- Suggested for JEDEC Level III and II for plastic IC packaging.
- NASA approved and is NON TOXIC—complying with USP Class VI Biocompatibility Standards.
- Capable of resisting TC wire bonding temperatures in the range of 300°C to 400°C.
- Ease of use; apply by dispensing, screen printing, die-stamping, or by hand.
- Especially suited for high power devices and high current flow. High power LEDs.
- Opto-electronic packaging material: LED, LCDs, and fiber optic components.

Typical Properties: (To be used as a guide only, not as a specification. Data below is not guaranteed. Different batches, conditions and applications yield differing results; Cure condition: 150°C/1 hour; *denotes test on lot acceptance basis)

Physical Properties:	
*Color: Part A: Silver Part B: Silver	Weight Loss:
*Consistency: Smooth, thixotropic paste	@ 200°C: 0.59%
*Viscosity (@ 100 RPM/23°C): 2,200 – 3,200 cPs	@ 250°C: 1.09%
Thixotropic Index: 3.69	@ 300°C: 1.67%
*Glass Transition Temp.(Tg): ≥ 80°C (Dynamic Cure 20—200°C /ISO 25 Min; Ramp -10—200°C @ 20°C/Min)	Operating Temp:
Coefficient of Thermal Expansion (CTE):	Continuous: -55°C to 200°C
Below Tg: 31 x 10 ⁻⁶ in/in/°C	Intermittent: -55°C to 300°C
Above Tg: 158 x 10 ⁻⁶ in/in/°C	Storage Modulus @ 23°C: 808,700 psi
Shore D Hardness: 75	Ions: Cl ⁻ 73 ppm
Lap Shear Strength @ 23°C: 1,475 psi	Na ⁺ 2 ppm
Die Shear Strength @ 23°C: > 5 Kg / 1,700 psi	NH ₄ ⁺ 98 ppm
Degradation Temp. (TGA): 425°C	K ⁺ 3 ppm
	*Particle Size: ≤ 45 Microns
Electrical Properties:	
*Volume Resistivity @ 23°C: ≤ 0.0004 Ohm-cm	
Thermal Properties:	
Thermal Conductivity: 29 W/mK	Thermal Resistance: (Junction to Case)
Based on Thermal Resistance Data: R = L x K ⁻¹ x A ⁻¹	TO-18 package with nickel-gold metallized 20 x 20 mil chips and bonded with EPO-TEK [®] H20E (2 mils thick)
	EPO-TEK [®] H20E: 6.7 to 7.0°C/W
	Solder: 4.0 to 5.0°C/W

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